

WHAT IS CLAIMED IS:

1. A semiconductor device comprising:

a semiconductor layer formed on an insulating surface, and having at least a source  
5 region, a drain region, and a channel formation region interposed therebetween;

a first insulating film formed on said semiconductor layer;

at least one electrode formed on said first insulating film, and overlapping said  
channel formation region;

a source wiring formed on said first insulating film;

10 a second insulating film covering at least said electrode and said source wiring;  
and

a gate wiring formed on said second insulating film, and connected to said  
electrode.

15 2. A semiconductor device according to claim 1, wherein said gate wiring overlaps  
a portion of said semiconductor layer containing at least said channel formation region.

3. A semiconductor device according to claim 1, wherein said electrode comprises  
a gate electrode.

20 4. A semiconductor device according to claim 1, wherein said electrode and said  
source wiring comprise a same material.

5. A semiconductor device according to claim 1, wherein a material of said gate  
25 wiring comprises one or a plurality of elements selected from the group consisting of poly-  
Si, W, WSi<sub>x</sub>, Al, Cu, Ta, Cr and Mo.

6. A semiconductor device according to claim 1, wherein said first insulating film  
comprises a gate insulating film.

7. A semiconductor device according to claim 1, wherein said second insulating film further comprises a first insulating layer containing silicon as a main component and a second insulating layer containing an organic resin material.

5           8. A semiconductor device according to claim 1, wherein said semiconductor device is one selected from the group consisting of a personal computer, a video camera, a portable information terminal, a digital camera, a digital video disk player, and an electric game appliance.

10           9. A semiconductor device comprising:  
a semiconductor layer formed on an insulating surface, and having at least a source region, a drain region, and a channel formation region interposed therebetween;  
a first insulating film formed on said semiconductor layer;  
at least one electrode formed on said first insulating film, and overlapping said  
15 channel formation region;  
a source wiring formed on said first insulating film;  
a second insulating film covering at least said electrode and said source wiring;  
a gate wiring formed on said second insulating film, and connected to said electrode;  
20 a connection electrode formed on said second insulating film, and connected to said source wiring and said semiconductor layer; and  
a pixel electrode formed on said second insulating film, and connected to said semiconductor layer.

25           10. A semiconductor device according to claim 9, wherein said pixel electrode overlaps said source wiring.

            11. A semiconductor device according to claim 9, wherein said gate wiring overlaps a portion of said semiconductor layer containing at least said channel formation region.

12. A semiconductor device according to claim 9, wherein said electrode comprises a gate electrode.

13. A semiconductor device according to claim 9, wherein said electrode and said source wiring comprise a same material.

14. A semiconductor device according to claim 9, wherein said pixel electrode, said connection electrode and said gate wiring comprise a same material.

15. A semiconductor device according to claim 9, wherein a material of said gate wiring comprises one or a plurality of elements selected from the group consisting of poly-Si, W, WSi<sub>x</sub>, Al, Cu, Ta, Cr and Mo.

16. A semiconductor device according to claim 9, wherein said first insulating film comprises a gate insulating film.

17. A semiconductor device according to claim 9, wherein said second insulating film further comprises a first insulating layer containing silicon as a main component and a second insulating layer containing an organic resin material.

18. A semiconductor device according to claim 9, wherein one pixel including said pixel electrode forms a storage capacitor between said semiconductor layer connected to said pixel electrode and said electrode connected to a gate wiring of an adjacent pixel, using said first insulating film as a dielectric.

19. A semiconductor device according to claim 9, wherein an impurity element for imparting a p-type conductivity is added to said semiconductor layer connected to said pixel electrode.

20. A semiconductor device according to claim 9, said semiconductor device is one selected from the group consisting of a personal computer, a video camera, a portable information terminal, a digital camera, a digital video disk player, and an electric game appliance.

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21. A semiconductor device comprising:

a first insulating film adjacent to a semiconductor layer, said semiconductor layer having at least a source region, a drain region, and a channel formation region interposed therebetween;

10 at least one electrode including a gate electrode formed on said first insulating film;

a source wiring formed on said first insulating film;

a second insulating film covering at least said electrode and said source wiring;

a gate wiring electrically connected to said electrode; and

15 a pixel electrode electrically connected to said semiconductor layer,

wherein said gate wiring and said pixel electrode are formed on said second insulating film.

22. A semiconductor device according to claim 21, wherein said gate wiring overlaps  
20 a portion of said semiconductor layer containing at least said channel formation region.

23. A semiconductor device according to claim 21, wherein said electrode and said source wiring comprise a same material.

25 24. A semiconductor device according to claim 21, wherein a material of said gate wiring comprises one or a plurality of elements selected from the group consisting of poly-Si, W, WSi<sub>x</sub>, Al, Cu, Ta, Cr and Mo.

25. A semiconductor device according to claim 21, wherein said first insulating film

comprises a gate insulating film.

26. A semiconductor device according to claim 21, wherein said second insulating film further comprises a first insulating layer containing silicon as a main component and  
5 a second insulating layer containing an organic resin material.

27. A semiconductor device according to claim 21, wherein said semiconductor device is one selected from the group consisting of a personal computer, a video camera, a portable information terminal, a digital camera, a digital video disk player, and an electric  
10 game appliance.

28. A semiconductor device comprising a pair of substrates and a liquid crystal interposed therebetween, one of said pair of substrates having at least a pixel portion and a driver circuit, said pixel portion comprising:

15 a semiconductor layer formed on an insulating surface, and having at least a source region, a drain region and a channel formation region interposed therebetween;

a first insulating film formed on said semiconductor layer;

at least one electrode formed on said first insulating film, and overlapping at least said channel formation region;

20 a source wiring formed on said first insulating film;

a second insulating film covering at least said electrode and said source wiring;

a gate wiring formed on said second insulating film, and connected to said electrode;

25 a connection electrode formed on said second insulating film, and connected to said source wiring and said semiconductor layer; and

a pixel electrode formed on said second insulating film, and connected to said semiconductor layer, and

wherein said other substrate comprises a light-shielding film in which a red color filter and a blue color filter are laminated so as to overlap said first semiconductor layer.

29. A semiconductor device according to claim 28, further comprising a common wiring on said second insulating film, wherein said pixel electrode and said common wiring are arranged so that an electric field substantially parallel to a surface of said substrate is generated.

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30. A semiconductor device according to claim 28, said semiconductor device is a reflection-type liquid crystal display device in which said pixel electrode comprises a film containing Al or Ag or a lamination film thereof.

10 31. A semiconductor device according to claim 28, said semiconductor device is a transmission-type liquid crystal display device in which said pixel electrode comprises a transparent electrically conductive film.

15 32. A semiconductor device according to claim 28, said semiconductor device is one selected from the group consisting of a personal computer, a video camera, a portable information terminal, a digital camera, a digital video disk player, and an electric game appliance.

20 33. A semiconductor device comprising a pair of substrates and a liquid crystal interposed therebetween, one of said pair of substrates having at least a pixel portion and a driver circuit, said pixel portion comprising:

a semiconductor layer formed on an insulating surface, and having at least a source region, a drain region and a channel formation region interposed therebetween;

a first insulating film formed on said semiconductor layer;

25 at least one electrode formed on said first insulating film, and overlapping at least said channel formation region;

a source wiring formed on said first insulating film;

a second insulating film covering at least said electrode and said source wiring;

a gate wiring formed on said second insulating film, and connected to said electrode;

and

a pixel electrode formed on said second insulating film, and electrically connected to said semiconductor layer.

5           34. A semiconductor device according to claim 33, further comprising a common wiring on said second insulating film, wherein said pixel electrode and said common wiring are arranged so that an electric field substantially parallel to a surface of said substrate is generated.

10           35. A semiconductor device according to claim 33, said semiconductor device is a reflection-type liquid crystal display device in which said pixel electrode comprises a film containing Al or Ag or a lamination film thereof.

15           36. A semiconductor device according to claim 33, said semiconductor device is a transmission-type liquid crystal display device in which said pixel electrode comprises a transparent electrically conductive film.

20           37. A semiconductor device according to claim 33, said semiconductor device is one selected from the group consisting of a personal computer, a video camera, a portable information terminal, a digital camera, a digital video disk player, and an electric game appliance.

          38. A method of manufacturing a semiconductor device comprising the steps of:  
          forming a semiconductor layer comprising a crystalline semiconductor film on an  
25   insulating surface;  
          forming a first insulating film on said semiconductor layer;  
          forming an electrode and a source wiring on said first insulating film, said electrode overlapping a portion of said semiconductor layer;  
          forming a second insulating film covering at least said electrode and said source

wiring; and

forming a gate wiring connected to said electrode and overlapping a portion of said semiconductor layer, a connection electrode for connecting said semiconductor layer to said source wiring, and a pixel electrode overlapping said source wiring,

5 wherein said gate wiring, said connection electrode, and said pixel electrode are formed on said second insulating film.

39. A method of manufacturing a semiconductor device of claim 38, wherein said second insulating film further comprises a lamination film of a first insulating layer made  
10 of silicon oxide, silicon nitride or silicon oxynitride and a second insulating layer made of polyimide, acrylic, polyamide, polyimide amide, or benzocyclobutene.

40. A method of manufacturing a semiconductor device of claim 38, wherein said semiconductor device is one selected from the group consisting of a personal computer, a  
15 video camera, a portable information terminal, a digital camera, a digital video disk player, and an electric game appliance.

41. A method of manufacturing a semiconductor device comprising the steps of:  
forming a first semiconductor layer and a second semiconductor layer on an  
20 insulating surface, each comprising a crystalline semiconductor film;  
forming a first insulating film on said first and second semiconductor layers;  
forming a first electrode overlapping said first semiconductor layer, a second electrode overlapping said second semiconductor layer, and a source wiring on said first insulating film;

25 forming a second insulating film covering at least said first and said second electrodes and said source wiring; and

forming a gate wiring connected to said first electrode and overlapping said first semiconductor layer, a connection electrode for connecting said first semiconductor layer to said source wiring, and a pixel electrode overlapping said source wiring,



wherein said gate wiring, said connection electrode, and said pixel electrode are formed on said second insulating film.

42. A method of manufacturing a semiconductor device of claim 41, wherein said second semiconductor layer connected to said pixel electrode overlaps said second electrode connected to a gate wiring of an adjacent pixel electrode.

43. A method of manufacturing a semiconductor device of claim 41, wherein said second insulating film further comprises a lamination film of a first insulating layer made of silicon oxide, silicon nitride or silicon oxynitride and a second insulating layer made of polyimide, acrylic, polyamide, polyimide amide, or benzocyclobutene.

44. A method of manufacturing a semiconductor device of claim 41, wherein said semiconductor device is one selected from the group consisting of a personal computer, a video camera, a portable information terminal, a digital camera, a digital video disk player, and an electric game appliance.